

AMENDMENTS TO THE CLAIMS

Please amend claims 1, 11, 18, 19, and 22, as follows.

Listing of Claims

1. (CURRENTLY AMENDED) A method of applying liquid to a substrate, comprising:
 - pumping liquid through a dispensing path in a manifold to a dispensing module;
 - intermittently cycling a dispensing valve of the dispensing module between an open condition for applying liquid from the dispensing module to the substrate and a closed condition for returning liquid from the dispensing module to a recirculation path in the manifold; and
 - preventing backflow of liquid from the recirculation path to the dispensing module when the dispensing valve is cycling from the open condition to the closed condition and the pressure of the liquid in the recirculation path is greater than the pressure of the liquid in the dispensing path.
2. (ORIGINAL) The method of claim 1, wherein the liquid is a hot melt adhesive.
3. (ORIGINAL) The method of claim 1, further comprising:
 - maintaining a pressure of liquid in the recirculation path greater than a pressure of liquid in the dispensing path as the dispensing valve is cycled from the open condition to the closed condition.